

Current and future FCC-ee vertex detector layouts and their performance

FCC-ee vertex detector R&D workshop, INFN Pisa

Armin Ilg¹

¹University of Zürich

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University of
Zurich^{UZH}



FUTURE
CIRCULAR
COLLIDER



Swiss National
Science Foundation

ZZ event at 240 GeV in IDEA detector concept [1]

Goal: Supreme impact parameter resolution: $\sigma_{d_0} = a \oplus b/(p \sin^{3/2} \theta) = 3 \oplus 15/(p \sin^{3/2} \theta) \mu\text{m}$

- Good single-hit resolution
- Material budget per layer of $\lesssim 0.3\% X_0$

→ So far, only monolithic active pixel sensors (MAPS) are envisioned to deliver this

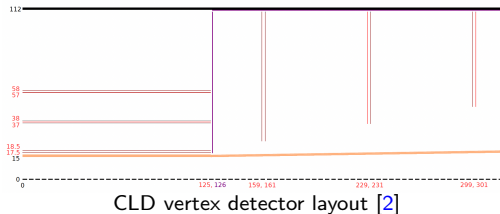
Layout

- Beam pipe as thin and light as possible
- (Inner) vertex detector: ≥ 3 hits per track, first layer as close as possible to IP
- Outer vertex in front of gas tracker: Up to ~ 35 cm in r (high hit rate, precise hit before tracker). Relaxed material budget and resolution requirements: **How relaxed?**
- Forward coverage constrained by lumical **Is a light pixel layer before lumical possible?**
- Redundancy in design, alignment, calibration... → **More/double layers?**

Collision environment at Z pole

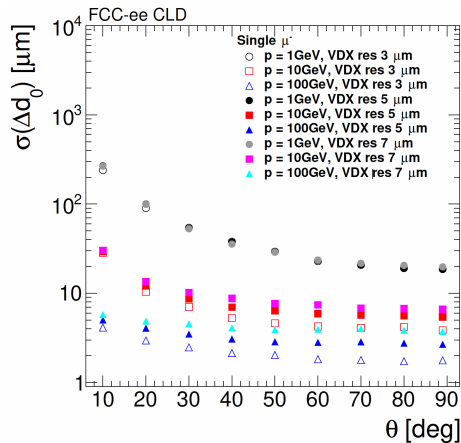
- Radiation tolerant components (less than HL-LHC), high hit rate (see [backup](#) for past studies)
- Tracking efficiency under beam background: **$\sigma_t < 20$ ns for bunch resolution and integration time $\leq 1 \mu\text{s}$? Much better for beam background rejection?**

CLD → Rescaled CLICDet vertex detector



→ Also currently used for ILD@FCC-ee

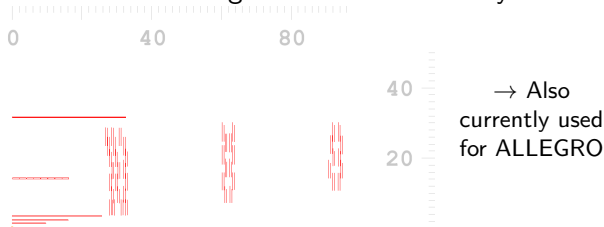
- $r_{\min} = 13 \text{ mm}$
- Three double-layer barrel layers and disks, 0.6–0.7% X_0 per double layer
- No engineering studies since CLICDet developments → Simple DD4hep full sim. implementation
- No specific sensor chosen, assume $3 \mu\text{m}$ single-point resolution



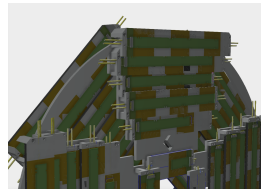
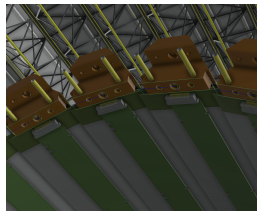
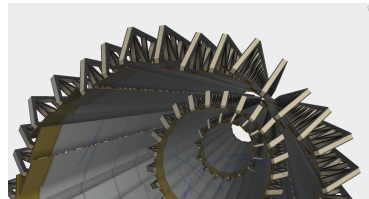
Full sim, CLD_o2_v05 [3]

→ $b \approx 18 \mu\text{m GeV}^{-1}$
 $3 \times 3 \mu\text{m}^2$ single-hit resolution is ok

IDEA → Original FCC-ee vertex layout

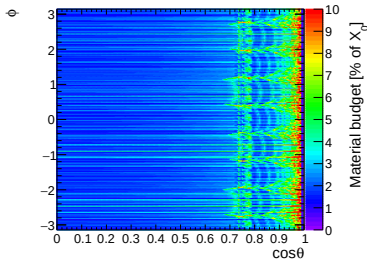
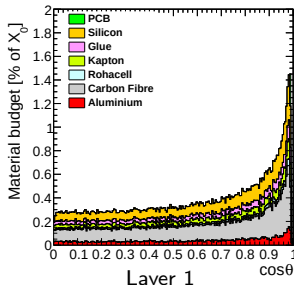
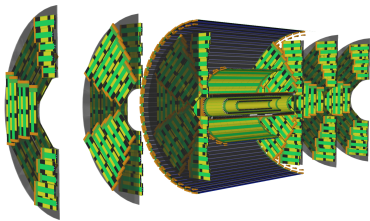


- $r_{\min} = 13.7 \text{ mm}$
- Three inner barrel single-layers ($0.25\% X_0$), two outer barrel layers and three disks
- Engineered design (INFN-Pisa) integrated into machine-detector interface (INFN-LNF [4])
- IDEA baseline: ARCADIA [5] (inner barrel, $25 \times 25 \mu\text{m}^2$) and ATLASPix3 [6] (outer barrel and disks, $150 \times 50 \mu\text{m}^2$) sensors

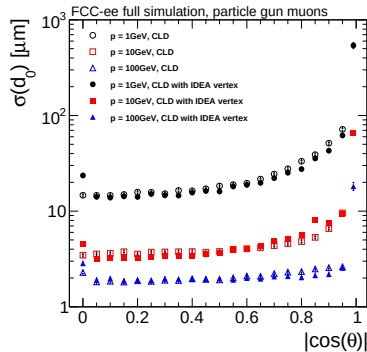


- Assume $3 \mu\text{m} / 14 \times 43 \mu\text{m}$ resolution for performance studies

- Detailed description of support and on-detector readout structures
- Insensitive sensor peripheries described → Check for hermeticity!



Complete vertex, 2D



IDEA vertex inserted in CLD using conformal tracking, [k4DetPerformance](#)

- $\cos(\theta) = 0$: No hit in first layer (gap between sensors)

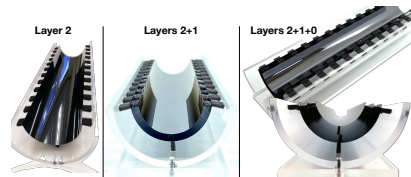
→ $b \approx 14 \mu\text{m GeV}^{-1}$

MAPS in 65 nm TPSCo process

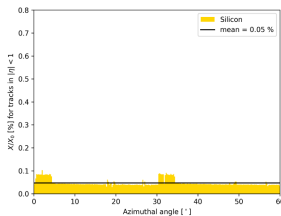
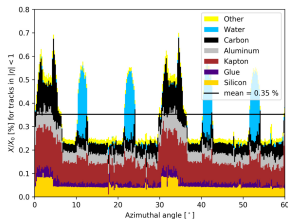
- More logic per cm^2
- Lower power consumption → Air cooling
- Enables 12-inch wafers → Wafer-scale bent sensors!

MAPS in 65 nm TPSCo process

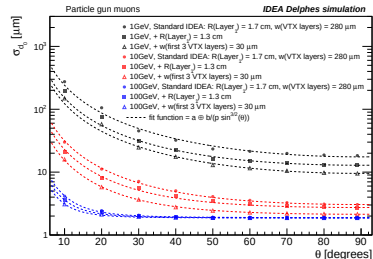
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Layer assembly concept for ALICE ITS3



Material budget in ALICE ITS2 (left, [7]) and silicon only (M. Mager)



Fast simulation study of reduced-material vertex detector variants [8]

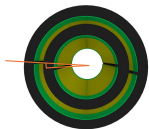
Layer 1 and 2: $r = 13.7, 20.35$ mm

- 10 and 13 repeated sensor units long $\rightarrow |\cos(\theta)| < 0.992/0.99$
- Peripheries, gap between half-barrels $\rightarrow$ Rotation in ϕ to fill gaps
- Readout and power from both sides

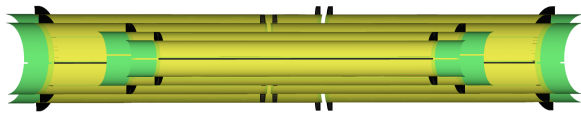
Layer 3 and 4: $r = 27, 33.65$ mm

- Two sensors per side, readout only on sides, power on sides and centre (power wire)
- 8 (10) RSUs on $+z$ ($-z$) side for layer 3, inverted for layer 4
 $\rightarrow |\cos(\theta)| < 0.991/0.986$

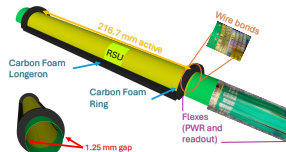
Assume $50 \mu\text{m}$ of Si + $16 \mu\text{m}$ of Si-equivalent (metal layer along sensor)



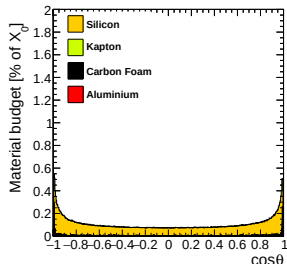
Layer 1+2 front



Longitudinal cross section of all four layers



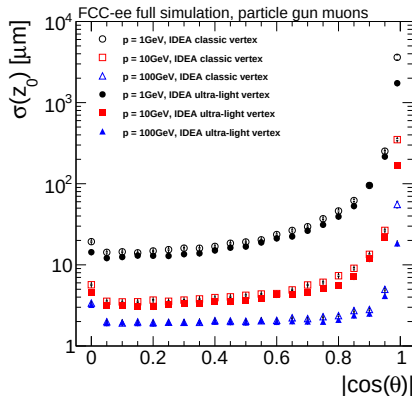
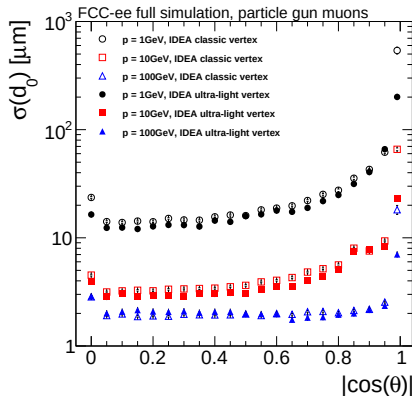
Layer 1 layout



Ultra-light layer 1

$0.075\% X_0$ at $\cos(\theta) = 0$

$\rightarrow > 3$ improvement!

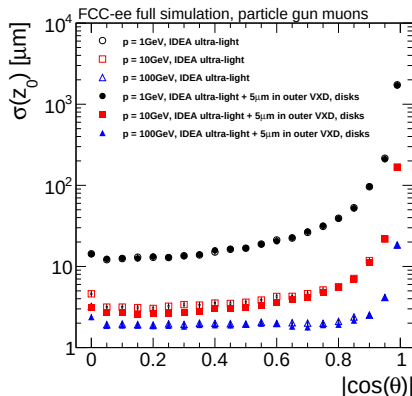
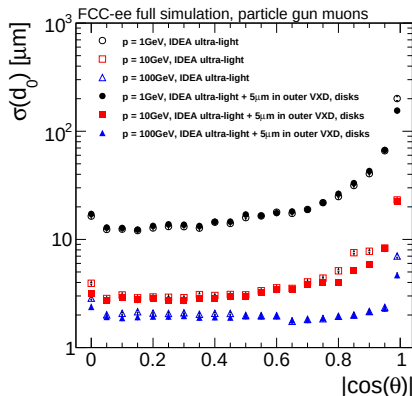


→ Significant improvements for low-momenta particles

- Even though there's no first layer hit in $\approx 10\%$ of the cases ($|\cos\theta| = 0$: 100%)
- $b \approx 12.5 \mu\text{m GeV}^{-1}$
- Reason for $\sigma(d_0)$ deterioration at 100 GeV unclear

IDEA middle ($r = 13$ cm) and outer barrel ($r = 31.5$ cm) and disks currently foresee ATLASPix3 sensors, with resolution of $43 \times 14 \mu\text{m}^2$ (pitch/ $\sqrt{12}$)

→ How good would IDEA vertex be if we had instead $5 \times 5 \mu\text{m}^2$ resolution?



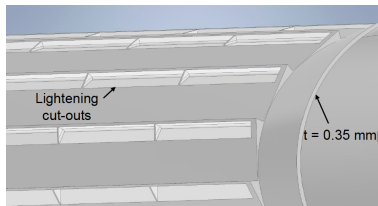
→ Improvement for 10, 100 GeV muons, deteriorated σ_{d_0} at 1 GeV (not yet understood)

• Full track reco in IDEA/ALLEGRO → Check impact on momentum resolution as well

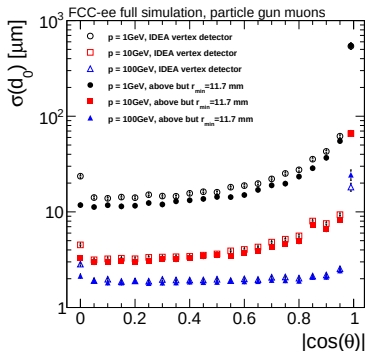
The first layer radius is important for the asymptotic impact parameter resolution (a)

Idea to put staves of sensors directly onto beam pipe

- Cooled through beam pipe cooling (paraffin) → Less air cooling needed
- Electrical insulation with kapton layer below sensor

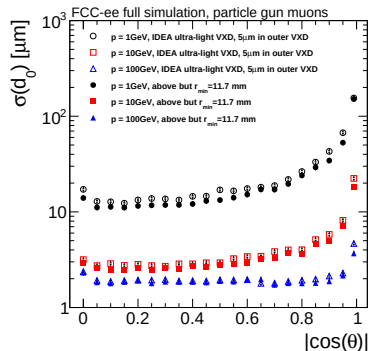


First design effort to move to $r = 11.7$ mm in IDEA ([G. Ammirabile](#))



IDEA classic

$$\rightarrow b \approx 12 \mu\text{m GeV}^{-1}$$



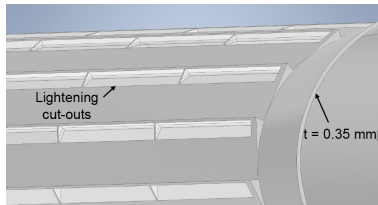
IDEA ultra-light

$$\rightarrow b \approx 11.8 \mu\text{m GeV}^{-1}$$

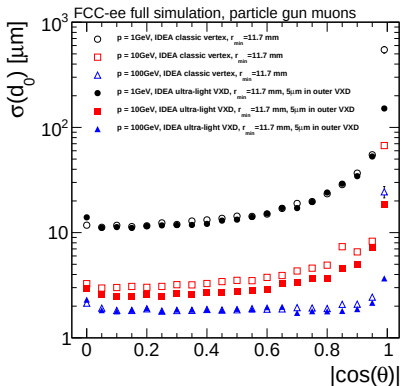
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→ $p = 10$ GeV: Significant benefit of low- X_0 VXD

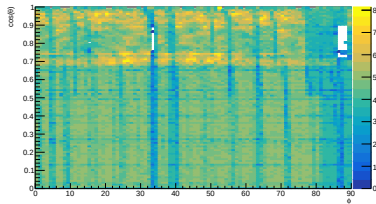
→ $p = 1$ GeV: Lower $r_{\min} \rightarrow$ Less travel distance for particles after scattering off beam pipe material → Better σ_{d_0}

Work with UZH summer student **Mohamed Ahmed**

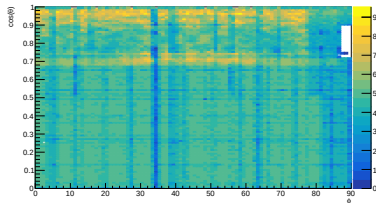
Gaps between the half-layers and peripheries within the the stitched sensor → Implemented exactly as in ITS3 TDR (93 % sensitive only, +2.5% without auxiliary pads)

Before rotation optimisation

Vertex Hits vs $\cos(\theta)$ and ϕ at 1 GeV/c

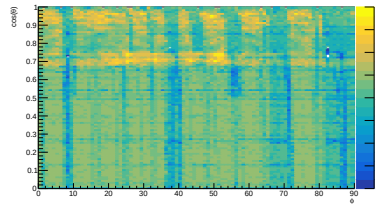


Vertex Hits vs $\cos(\theta)$ and ϕ at 10 GeV/c

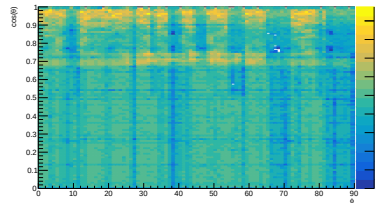


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Vertex Hits vs $\cos(\theta)$ and ϕ at 1 GeV/c

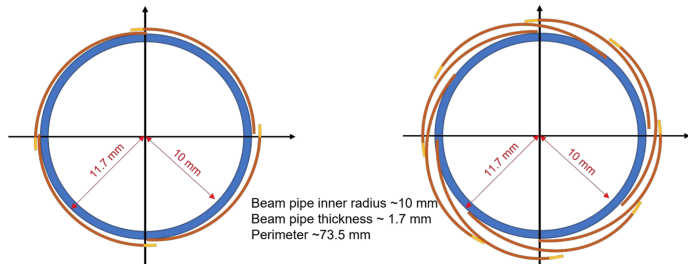


Vertex Hits vs $\cos(\theta)$ and ϕ at 10 GeV/c



Snail-shape vErtEx Detector (FCC-SEED) proposal by French institutes, also submitted as
FCC Detector R&D EoI

- Stitching only along z , overlap between curved sensors $\rightarrow$ Full detector coverage
- More flexible in sensor size and detector layout
- So far looked at option on the left



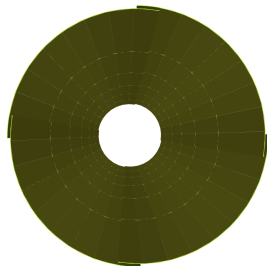
See A. Besson and J. Andrea's talk at 8th FCC Physics Workshop

Layer	1	2	3	4	5
Radius (mm)	12-13	24	36	48	60
Zmax (mm)	90	120	120	120	120
Perimeter (mm)	75	151	226	302	377
# Chips per ladder	6	8	8	8	8
# ladders	4	8	12	16	20

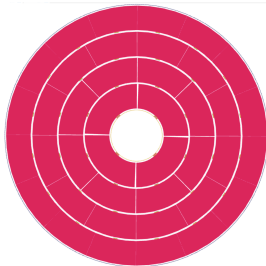
Layer	1-2	3-4	5-6
Radius (mm)	12-13	35-36	59-60
Zmax (mm)	90	120	120
Max perimeter (mm)	82	226	377
# Chips per ladder	6	8	8
# ladders	4	12	20

Single chip dimension	$30 \times 22.2 \text{ mm}^2$
Sensitive area chip dimension	$30 \times 19.2 \text{ mm}^2$

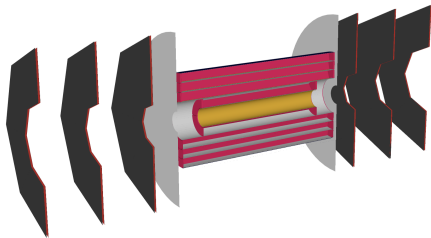
$\rightarrow$ Implemented FCC-SEED in DD4hep and tested it within CLD detector concept (vertex disks unchanged currently).



First layer sensors only



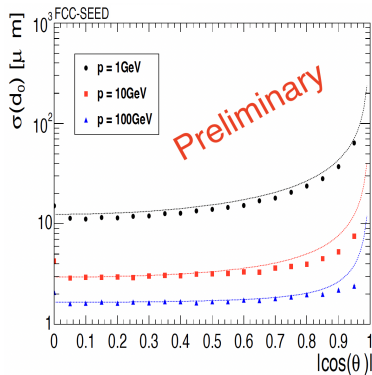
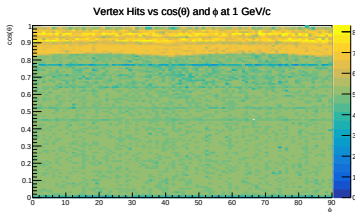
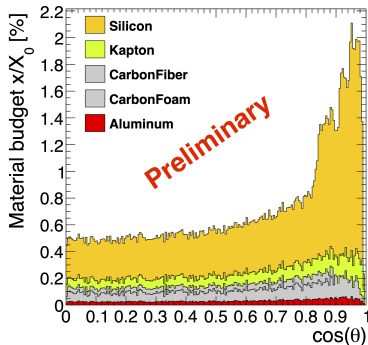
Carbon foam rings



Work with UZH summer student **Mohamed Ahmed**

- First layer at $r_{\min}$ of 11.8 mm, after 100 μm of Kapton
- Carbon foam longerons and rings, similar to ultra-light VXD design
- Thin layer of carbon fibre between sensors, flex (same as in IDEA inner vertex) on top of periphery
- Outer carbon fibre shell (same as in IDEA inner vertex)
- No off-detector services or supports or "end-of-stave" structures yet

Work with UZH summer student **Mohamed Ahmed**



- $0.5\% X_0$ in five layers $\rightarrow 0.1\% X_0$ per layer

$\rightarrow b \approx 11.1 \mu\text{m GeV}^{-1}$ for $r_{\min} = 11.8 \text{ mm}$

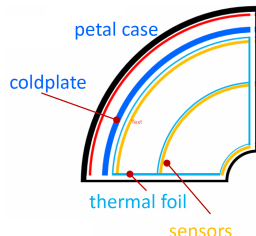
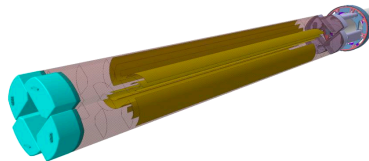
Next steps: MR to k4geo, revisit stitching gaps, replace CLD disks, optimise (reduce) support material, add cables/fibres and end-of-ladder structure

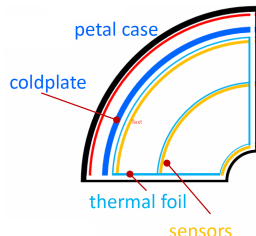
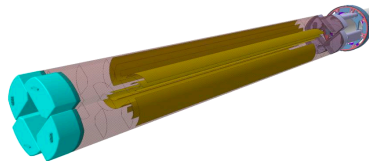
Detailed presentation in [last detector concept meeting](#)

ALICE ITS3 is cool. But what about ALICE3?

ALICE3 IRIS

- $r_{\min} = 5$ mm, retractable
- 3 curved layers of sensors, 4 secondary vacuua
- Retractable to increase $r_{\min} \rightarrow$ During LHC filling
- Liquid CO₂ cooling ($T_{\text{sensor}} \sim -25^\circ\text{C}$)
- Secondary beam pipe of only 300 μm Be thickness (FCC-ee: 700 μm of AlBeMet167 + 1 mm of paraffin)



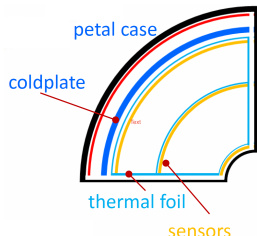
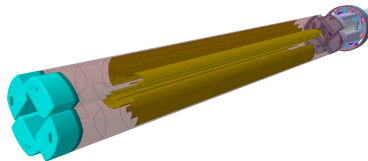


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Considerations for FCC-ee

- $r_{\min}$ not below 10 mm
- Maybe 4 layers, and 1–2 sec. vacuua?
- Retractability prob. not useful (top-up injection)
- T_{room} ok for sensors
- Beam power @ ALICE3: $\sim 30 \text{ W m}^{-1}$ (FCC-ee: $\sim 300 \text{ W m}^{-1}$)
- IPC hit rate tolerable?

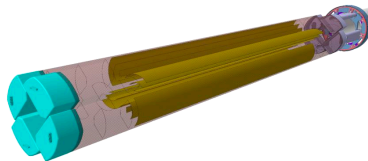


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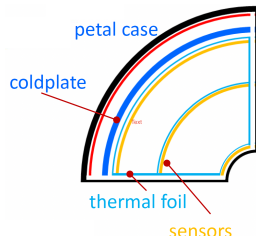
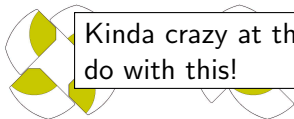
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Kinda crazy at the moment... But just for fun... Let's see what we could do with this!

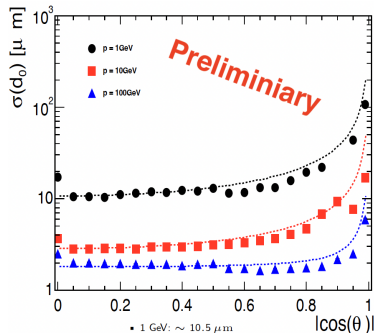
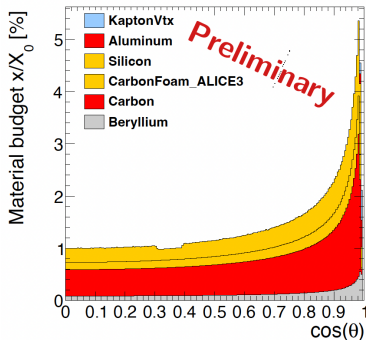
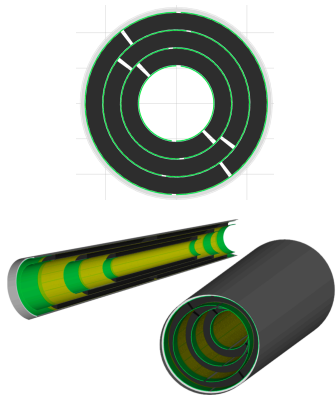


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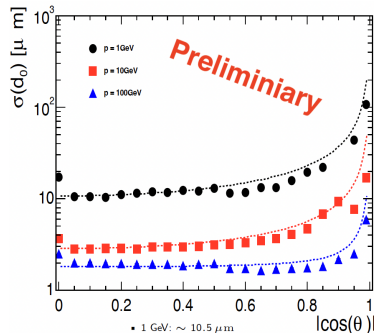
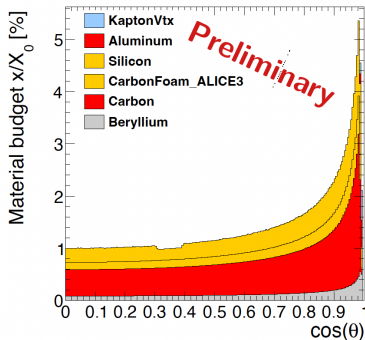
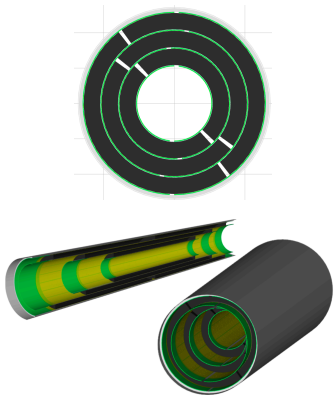
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Work with UZH summer student **Mohamed Ahmed**



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$b \approx 10.5 \mu\text{m GeV}^{-1}$ achieved, expected a bit better $\rightarrow$ Under investigation
 Would need many more studies to see if feasible/worth it at FCC-ee!

$\mathcal{O}(10\ \mu\text{m})$ in r - ϕ for momentum resolution

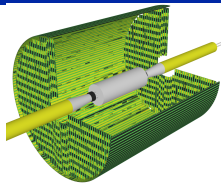
- Disk: Expand tracker coverage in forward region. $\mathcal{O}(10\ \mu\text{m})$ in θ for precise detector acceptance definition?
- Is resolution of $\mathcal{O}(100\ \mu\text{m})$ in z (barrel) enough? Benefit of $\mathcal{O}(10\ \mu\text{m})$?
- Potentially σ_t of $\mathcal{O}(\leq 100\ \text{ps})$ for PID
→ Silicon microstrip, LGADs, or MAPS?

Implemented silicon wrapper in DD4hep

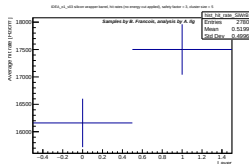
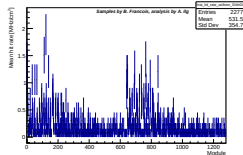
- Two barrel and disks, ≥ 2 hit down to $|\cos\theta| < 0.989$
- Tiles with large ($4 \times 4\ \text{cm}^2$) sensors
- Next iteration: One layer, rings in disks

Questions:

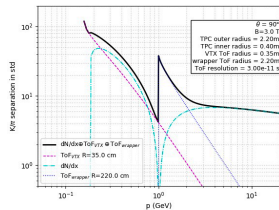
- Inner timing layer as well?
- Same technology as outer vertex possible?



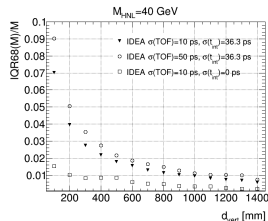
Complete SiWr in DD4hep



Hit rate in first SiWr disk (top) and barrel (bottom)



Outer + inner TOF at 3 T



Relative mass resolution on HNL as a function of its flight distance [9]

About vertex detector layouts:

- $r_{\min}$ crucial also for low-momentum tracks. **First layer on beam pipe? Secondary vacuum?**
 - Limited by IPC hit rate and cooling → Also influences sensor choice (charge sharing)
- Non-hermetic layers don't prevent good IP resolutions, but advantages of hermetic design clearly visible (especially for first layer)
- Good spatial resolution in outer vertex desirable
 - **What material budget can we afford there? Liquid or air cooling?**
 - **Inner T.O.F layer? Which technology?**
- **Benefit of close-to-IP disks? Potential benefits of pixel sensors in front of lumical?**
- Redundancy in design: **How many layers, double-sided?**

About MAPS:

- Optimise power consumption (enabling air cooling)
- Minimisation of periphery → Lower material budget (stave-like design) or better hermeticity (2D-stitched designs)
- **Timing: $\sigma_t < 20 \text{ ns}$ and $t_{\text{int}} \leq 1 \mu\text{s}$? Background rejection?**

2025 – 2027: Explore various kinds of vertex detector concepts and layouts, develop tools necessary to enable efficient comparison

Vertex detector concepts comparison

- Interfacing sensor simulation (from TCAD or AllPix2) with detector full simulation to realistically evaluate final tracking and vertexing performance
 - Establishing figures of merits evaluation workflow (incl. case study designs)
 - Establish workflow for machine background study
- First rough exploration of vertex detector phase space

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I think that's still what we should do to answer questions on previous slide. Progress on all points is ongoing.

2025 – 2027: Explore various kinds of vertex detector concepts and layouts, develop tools necessary to enable efficient comparison

Vertex detector concepts comparison

- Interfacing sensor simulation (from TCAD or AllPix2) with detector full simulation to

real *2028 – 2030: Narrow down to just a couple of vertex detector concepts*

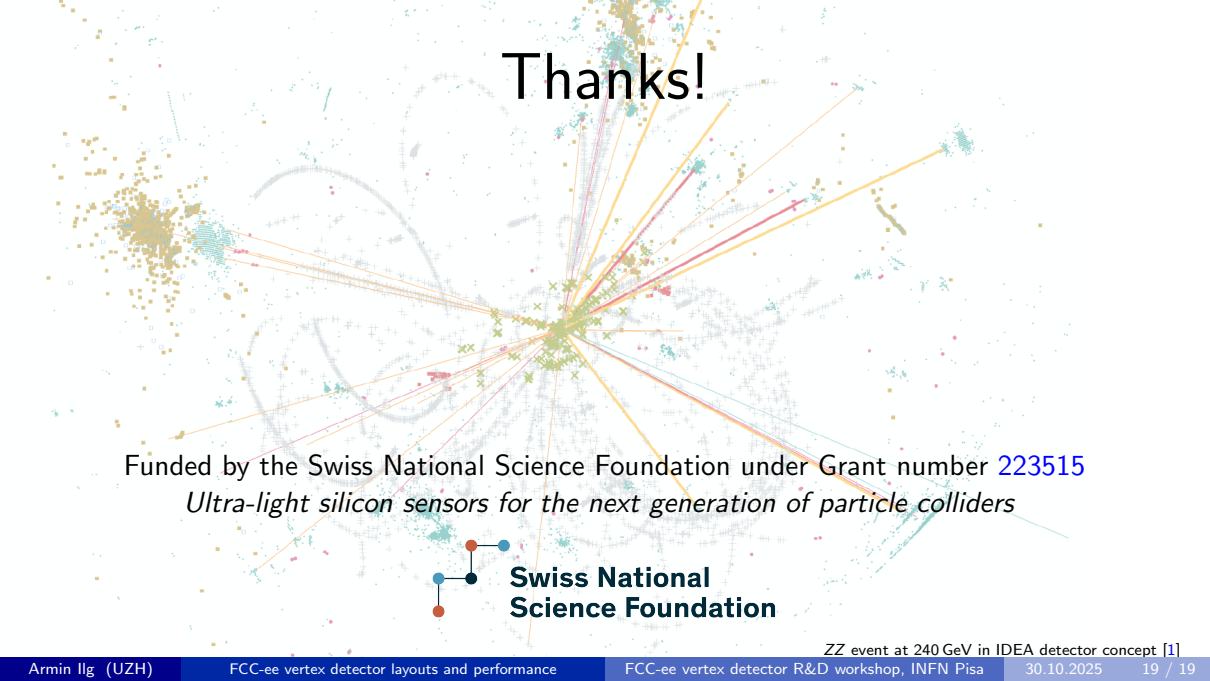
- Establish *as input to detector CDRs, and to be studied in more detail in the TDR*

phase

- Establish *benchmark for machine background study*

→ First rough exploration of vertex detector phase space

I think that's still what we should do to answer questions on previous slide. Progress on all points is ongoing.

The background of the slide is a complex particle detector simulation. It features a central region with a high density of green 'x' marks, from which numerous colored lines (orange, red, blue, green) radiate outwards. These lines represent particle tracks. The entire scene is overlaid with a faint, circular grid of small grey crosses, suggesting a detector's cross-sectional view or a coordinate system. The overall color palette is dominated by the green of the central cluster and the various colors of the radiating tracks.

Thanks!

Funded by the Swiss National Science Foundation under Grant number [223515](#)
Ultra-light silicon sensors for the next generation of particle colliders

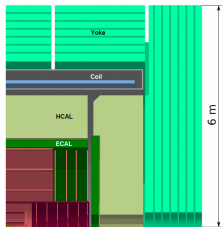


**Swiss National
Science Foundation**

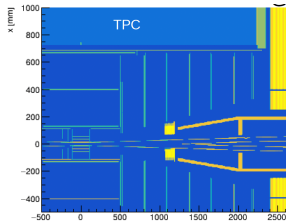
- [1] IDEA Study Group Collaboration, M. Abbrescia et al., *The IDEA detector concept for FCC-ee*, [arXiv:2502.21223 \[physics.ins-det\]](#).
- [2] N. Bacchetta, et al., *CLD – A Detector Concept for the FCC-ee*, [arXiv:1911.12230 \[physics.ins-det\]](#).
- [3] G. Sadowski, J. Andrea, A. Besson, and Z. E. Bitar, *Tracking Performance Studies for Future Circular Collider (FCCee) with CLD Detector*, [EPJ Web Conf. **315** \(2024\) 03003](#).
- [4] M. Boscolo, et al., *Progress in the design of the future circular collider FCC-ee interaction region*, [JACoW IPAC 2024 \(2024\) TUPC67](#).
- [5] C. Neubüser, T. Corradino, G.-F. Dalla Betta, and L. Panzeri, *ARCADIA FD-MAPS: Simulation, characterization and perspectives for high resolution timing applications*, [Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment **1048** \(2023\) 167946](#).
- [6] I. Peric, et al., *High-Voltage CMOS Active Pixel Sensor*, [IEEE Journal of Solid-State Circuits **56** \(2021\) 2488–2502](#).
- [7] F. Reidt, *Upgrading the Inner Tracking System and the Time Projection Chamber of ALICE*, [Nuclear Physics A **1005** \(2021\) 121793](#).
- [8] L. Freitag, *Benefits of Minimizing the Vertex Detector Material Budget at the FCC-ee*, 2023.
<https://cds.cern.ch/record/2851362>. Presented 01 Feb 2023.
- [9] W. Bartmann, et al., *Future Circular Collider Feasibility Study Report Volume 1: Physics and Experiments*, 2025.
<http://cds.cern.ch/record/2928193>.
- [10] ILD Collaboration, U. Einhaus, *The International Large Detector (ILD) for a future electron-positron collider: Status and Plans*, [PoS EPS-HEP2023 \(2024\) 543](#), [arXiv:2311.09181 \[hep-ex\]](#).
- [11] M. Aleksa, et al., *Calorimetry at FCC-ee*, [The European Physical Journal Plus **136** \(2021\) 1066](#).
- [12] X. Mo, G. Li, M.-Q. Ruan, and X.-C. Lou, *Physics cross sections and event generation of e^+e^- annihilations at the CEPC*, [Chinese Physics C **40** \(2016\) 033001](#), <https://doi.org/10.1088/1674-1137/40/3/033001>.

- [13] A. Ciarma, M. Boscolo, G. Ganis, and E. Perez, *Machine Induced Backgrounds in the FCC-ee MDI Region and Beamstrahlung Radiation*, *Proceedings of the 65th ICFA Advanced Beam Dynamics Workshop on High Luminosity Circular e+e- Colliders eeFACT2022* (2022) Italy, <https://jacow.org/eefact2022/doi/JACoW-eeFACT2022-TUZAT0203.html>.
- [14] D. Garcia, B. Francois, M. Selvaggi, and A. De Vita, *Geometric Graph Neural Network based track finding*, <https://repository.cern/doi/10.17181/pwrx1-wvn43>.
- [15] E. Brondolin, et al., *Conformal tracking for all-silicon trackers at future electron-positron colliders*, *Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment* **956** (2020) 163304, <http://dx.doi.org/10.1016/j.nima.2019.163304>.

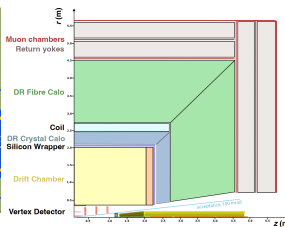
FCC-ee detector *concepts* (modulo some variations)



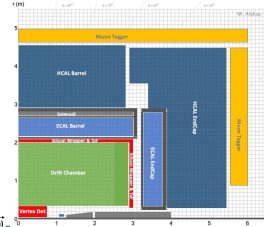
CLD [2]



ILD [10]



IDEA [1]



ALLEGRO [11]

- Light silicon vertex detector using monolithic active pixel sensors (MAPS)

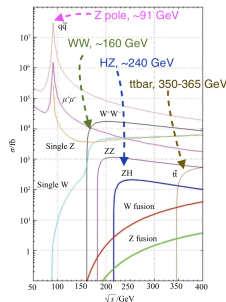
- Si tracker
- dE/dx + ARC (?)
- CALICE-like highly-granular ECAL/HCAL
- Solenoid coil outside calorimeter system
- Si tracker + time projection chamber
- Si or ECAL with T.O.F
- CALICE-like highly-granular ECAL/HCAL
- Solenoid coil outside calorimeter system
- Ultra-light drift chamber with $dN_{ion.}/dx$
- Si layer with T.O.F
- Dual-readout crystal ECAL
- Light solenoid up to 3 T
- DR fibre HCAL
- DC/SciFi/Straw tubes
- Si layer with T.O.F
- Noble liquid ECAL, Pb/W+LAr or W+LKr
- Solenoid in same cryostat as ECAL
- TileCal HCAL
- Muon system in return yoke, pretty much det. concept independent (e.g. μ -RWELL in IDEA)

Experimental environment at the FCC-ee (Z pole)

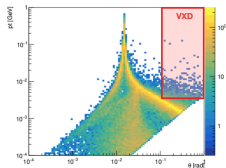
☺: e^+e^- collisions are *clean* - there's no QCD in the initial state

☹: Very high inst. luminosity of $140 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$ thanks to 37 MHz bunch collision rate ($t_{\text{BC}} = 27 \text{ ns}$ currently)

- Very high rate of interesting events (60 kHz of Z, 18 kHz of $\gamma\gamma \rightarrow$ hadrons, 30 kHz of bhabha pairs) that need to be read out and saved (and simulated!)
- "Pile-up" Z bosons of $\sim 60 \text{ kHz}/50 \text{ MHz} = 0.00162$
 - Integrate over of a couple of bunch crossings?
 - But need to check impact on uncertainties
- Considerable beam backgrounds, mainly from incoherent pairs
 - High hit rate innermost vertex layers, occupancy challenges in gaseous tracker and ECAL
 - Challenge also for readout
 - Few $10^{13} \text{ 1 MeV } n_{\text{eq}}\text{cm}^{-2}$ and few tens of kGy per year in vertex detector



e^+e^- annihilation
cross section [12]



Incoherent pairs at Z
pole [13]

Common assumptions so far:

- Incoherent pair creation (IPC) dominant. Radiative Bhabha scattering, synchrotron radiation, beamstrahlung are much lower
 - IPC simulated in GuineaPig MC generator and interfaced with Key4hep
- SIM hit to REC hit: Cluster size of 5, safety factor of 3, $25 \times 25 \mu\text{m}^2$ pixels

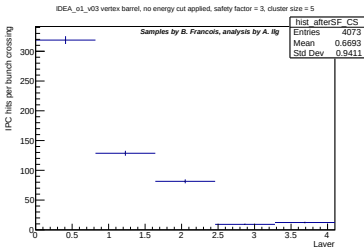
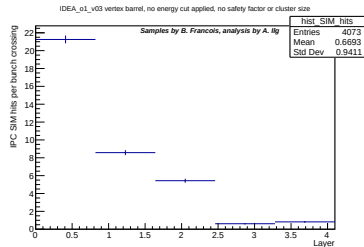
Occupancy and hit rates:

- 2022, old lattice with 30 ns bunch spacing, CLD vertex detector, 70×10^{-6} per BC $\hat{=}$ 373 MHz cm⁻² [13]
- 2024, V23 lattice, IDEA vertex detector: 20×10^{-6} per BC $\hat{=}$ 170 MHz cm⁻²
- 2024, V23 lattice, ultra-light vertex detector: 30×10^{-6} per BC $\hat{=}$ 250 MHz cm⁻²
- 2025, V23 lattice, IDEA vertex detector with CAD beam pipe, GuineaPig particles set to (0,0,0), *SIM.filter.tracker* = "edep0": 11×10^{-6} per BC $\hat{=}$ 90 MHz cm⁻², but bug in CAD beampipe (Air inside), samples by B. Francois

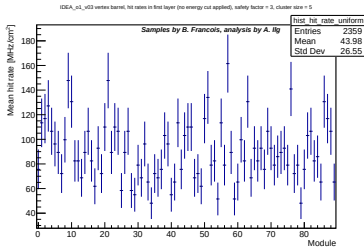
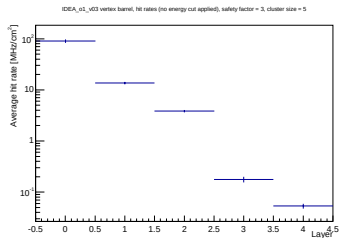
Expect further updates and changes!

- Always highest at Z pole in innermost barrel and disk, rather flat along z and ϕ (see [here](#))

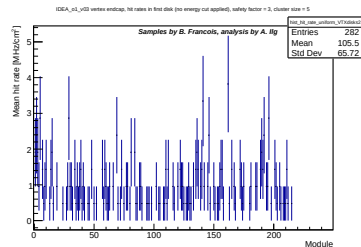
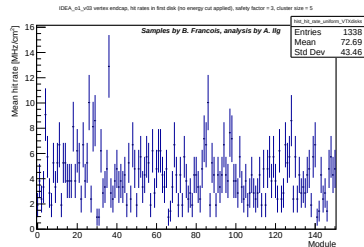
SIM hits

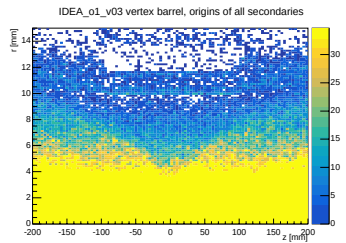
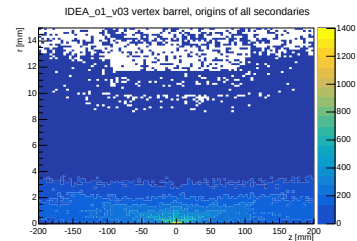
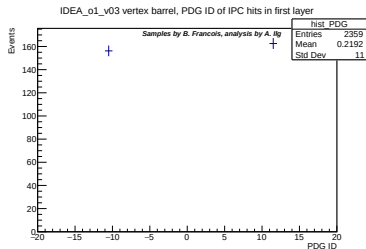
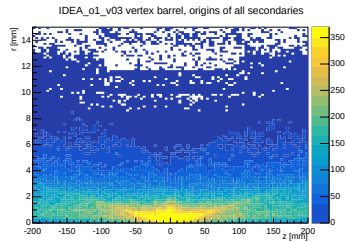
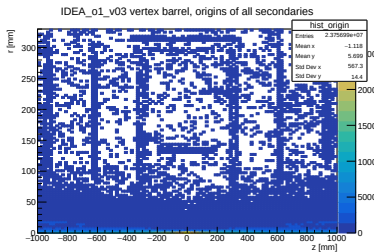
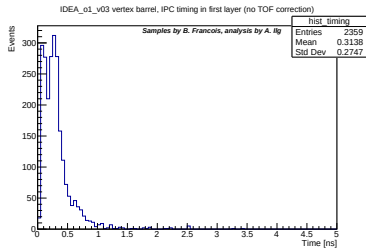


Vertex barrel hit rates

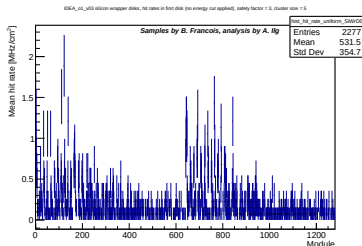


Vertex disk hit rates

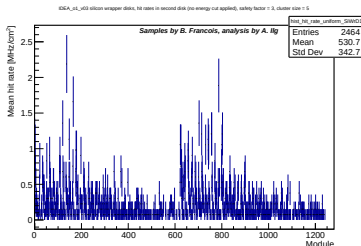




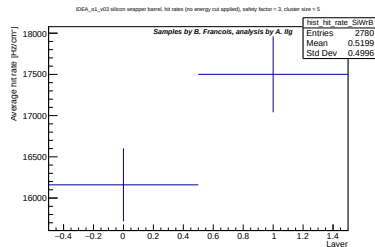
SiWr disk 0



SiWr disk 1



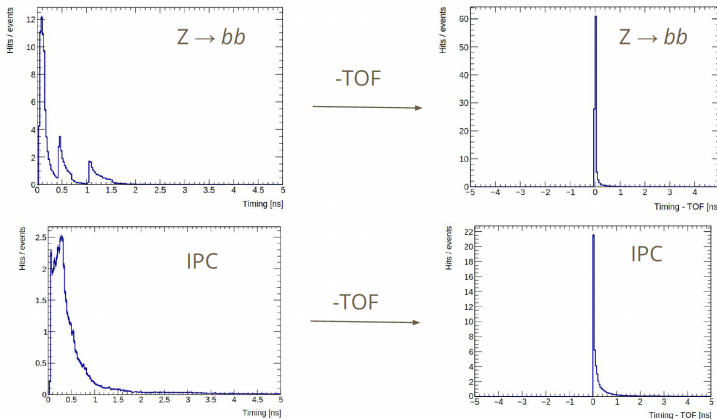
SiWr barrel



Disks: Assuming same tile size for all tiles (not true) → Overestimating hit rate in outer tiles

Timing of hits

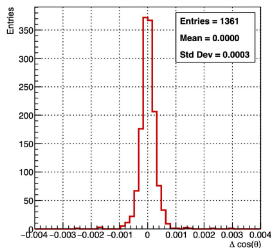
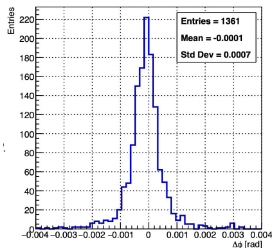
N.B. timing of IPC may be misleading, we move all particles at the origin!



Work in progress, R. Simonielli, A. Koulouris, S. Franchellucci

Algorithmic reconstruction using Genfit2

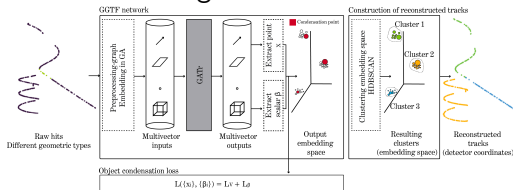
- Providing track representation, track-fitting algorithms and graphic visualization
- Relying on ground truth



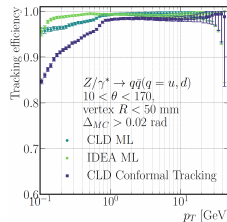
Vertex + drift chamber reco, $E = 5 \text{ GeV}$, θ between 15° and 80° , A. de Vita @ FCC Week 2025

ML-based track reconstruction

- GNN, detector agnostic
- Track refitting to be done still



$$\text{Object condensation loss} \\ L(\mathbf{u}), \{\mathbf{B}\} = L_v + L_o$$



Tracking efficiency [14]

For CLD, simply use conformal tracking [15] (see [talk by Leonhard](#))

For IDEA, eventually use

- ACTS tracking ([talk by Samuel](#)) → Not yet available for IDEA
- Genfit2 tracking or ML tracking ([talk by Andrea](#)) → Track refitting not yet done

For the moment simply insert IDEA vertex detector into CLD_o2_v05 and use conformal tracking!

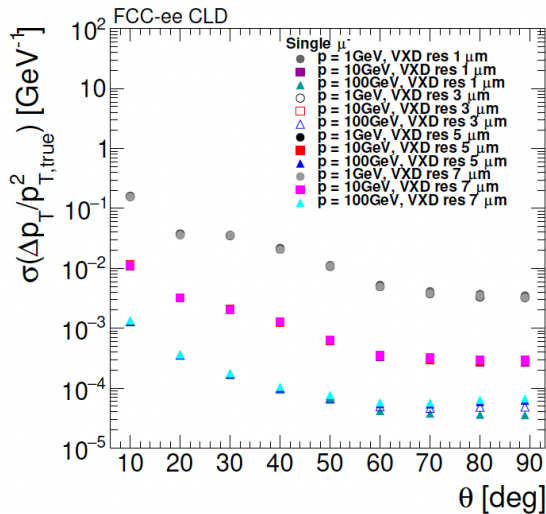
Necessary changes

- Removing first Inner Tracker barrel layer ($r = 127$ mm)
- Removing first and second Inner Tracker disks ($r = 79.5$ and 123.5 mm)
- Unchanged conformal tracking max. distance (CT_MAX_DIST) and *MinClustersOnTrack*

Nota bene

- Tracking performance should be much better with drift chamber and silicon wrapper
- Assume spatial resolution of $3\text{ }\mu\text{m}$ for inner vertex barrel (same as CLD), and $14\text{ }\mu\text{m} \times 43\text{ }\mu\text{m}$ for outer barrel and disks (CLD: vertex endcap: $3\text{ }\mu\text{m}$, inner tracker endcap: $5\text{ }\mu\text{m}$ or $7 \times 90\text{ }\mu\text{m}$)

Not perfect, but works, reasonably meaningful for impact parameter resolution comparison



[3]